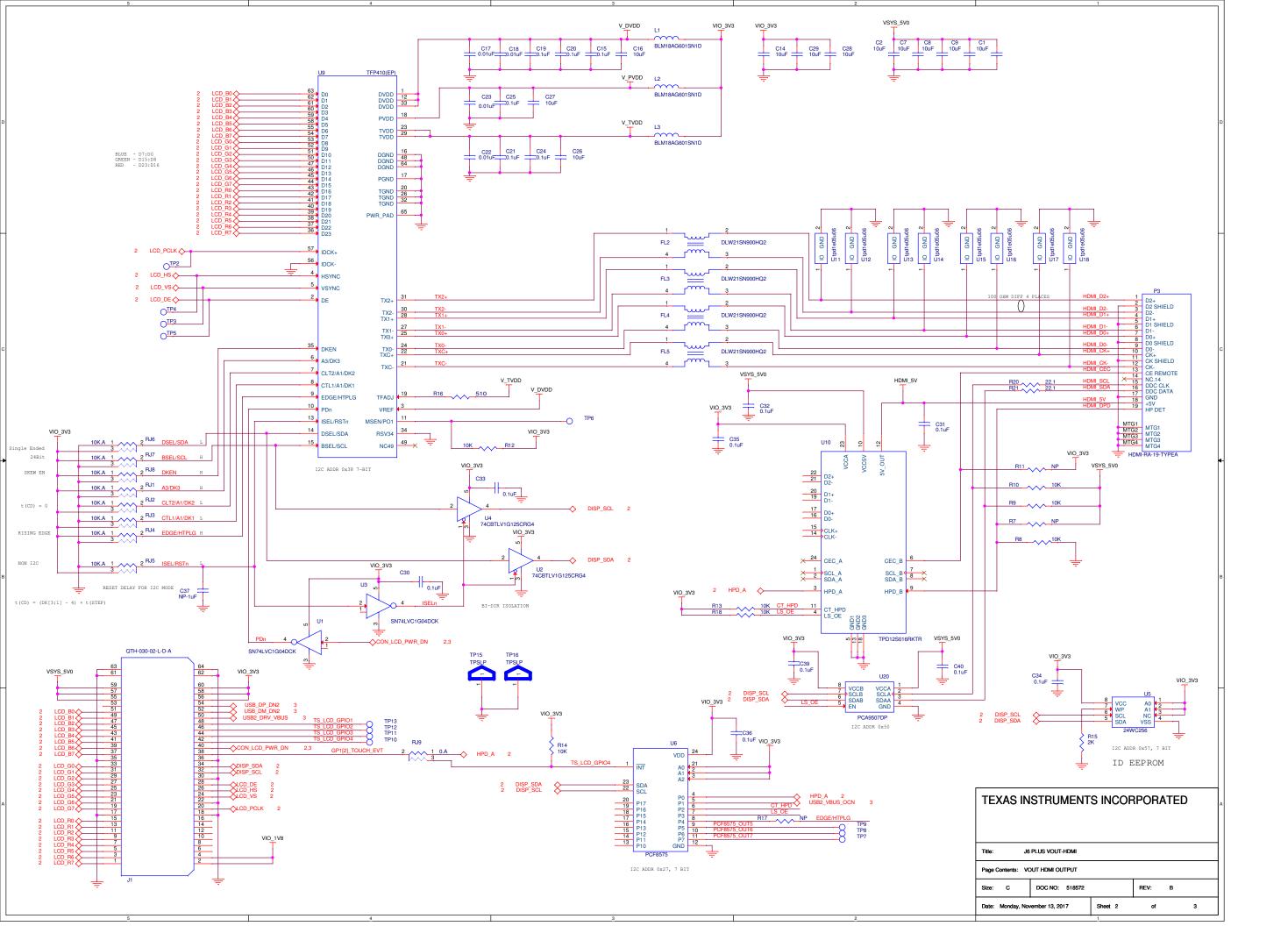
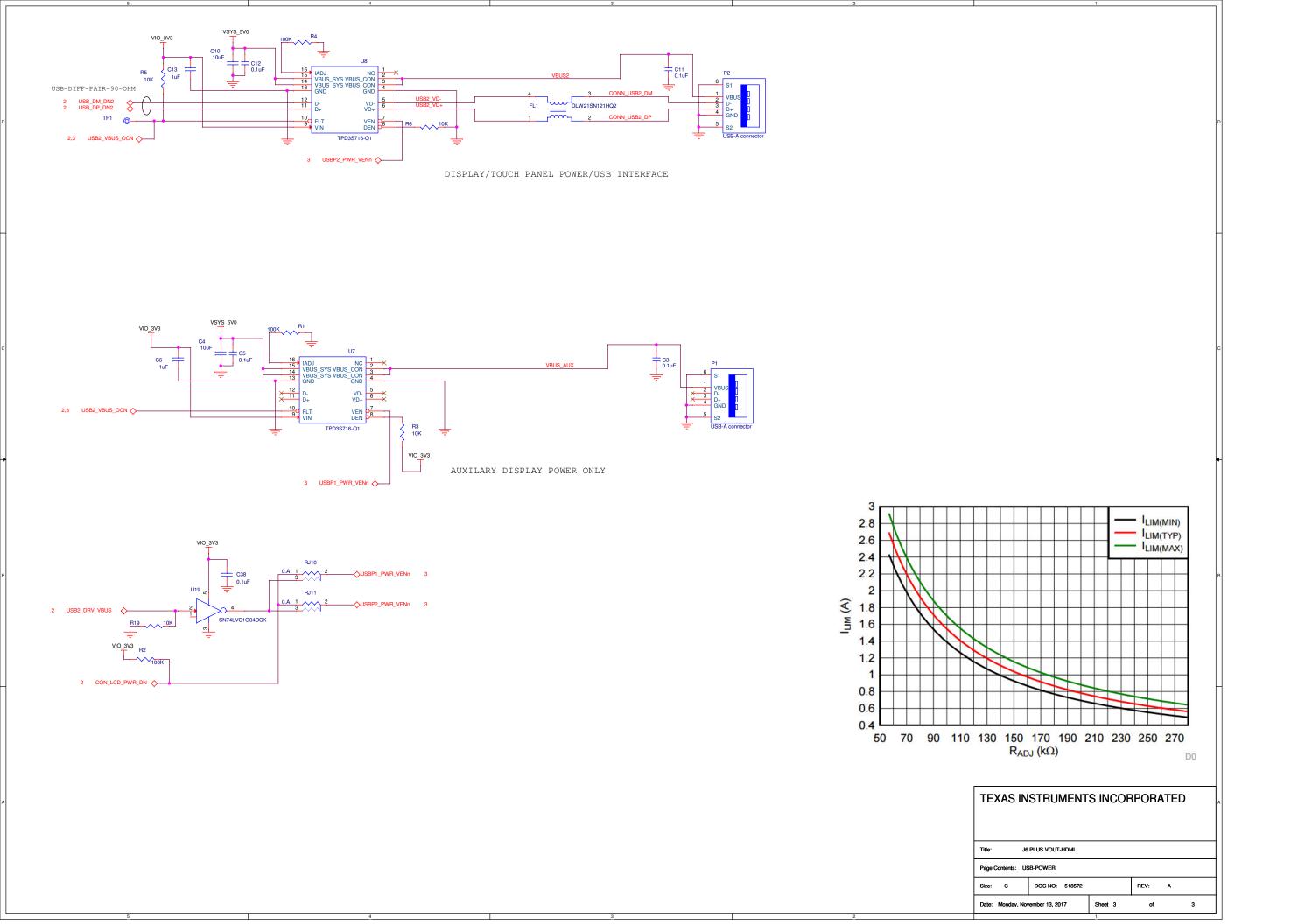
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	CHANG:	CHANGES E EDID 12C ISOLATION TO PCA9507DP. PP12S016RKTR A-SIDE Vol DOES NOT DRIVE LO H TO MEET J6 PLUS Vil ON THE SDA SIGNAL.	W	C 8
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DWN DATE J.A.C 05/03/2017 CHK DATE				
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